

APPLICATION DATA SHEET

Application Information

Application Type:: Regular
Subject Matter:: Utility
Title:: Lead Frame, Resin Sealing Mold And Method For Manufacturing A Semiconductor Device Using The Same
Attorney Docket Number:: 2905-107
Request for Early Publication?:: No
Request for Non-Publication?:: No
Total Drawing Sheets:: Fifteen (15)
Small Entity:: No
Petition included?:: No
Secrecy Order in Parent Appl?:: No

Applicant Information

Applicant Authority type:: Inventor
Primary Citizenship Country:: Japan
Status:: Full Capacity
Given Name:: Isao
Middle Name:: -----
Family Name:: Ochiai
City of Residence:: Gunma
Country or Residence:: Japan
Street of mailing address:: 11-14, Kumano-cho, Ota-city
City of mailing address:: Gunma

Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Kazumi
Middle Name::	-----
Family Name::	Onda
City of Residence::	Saitama
Country or Residence::	Japan
Street of mailing address::	2624, Mitakaya, Hanyu-city
City of mailing address::	Saitama

Assignment Information

Assignee name:: Sanyo Electric Co., Ltd.
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City of mailing address:: Osaka
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Correspondence Information

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Domestic Priority Information

Application::	Continuity Type:	Parent Application:	Parent Filing Date:
This Application	Divisional	10/291,815	11/12/02

Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2002-020296	01/29/02	Yes
Japan	2001-346408	11/12/01	Yes

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